

ULTRA-THIN COPPER FOIL WITH CARRIERS, METHOD OF
PRODUCTION OF SAME, AND PRINTED CIRCUIT BOARD USING
ULTRA-THIN COPPER FOIL WITH CARRIERS

5

ABSTRACT OF THE DISCLOSURE

An ultra-thin copper foil with a carrier having a peeling layer able to withstand even high temperature working in the case of using a high heat resistant resin, enabling the carrier foil and the ultra-thin copper foil to be easily peeled apart, and reduced in the number of pinholes by uniform plating without impairing the peelability of the peeling layer, that is, an ultra-thin copper foil with a carrier comprised of a carrier foil, a peeling layer, and an ultra-thin copper foil, wherein the peeling layer and the ultra-thin copper foil are provided between them with a strike plating layer at the surface on the peeling layer side, an ultra-thin layer of copper is provided on this according to need, and an ultra-thin copper foil comprised of copper or a copper alloy or a phosphorus-containing copper or phosphorus-containing copper alloy is provided. The peeling layer between the carrier foil and the ultra-thin copper foil is chromium, a chromium alloy, a chromium-containing oxide hydrate

layer, nickel, iron, or an alloy layer of the same or an oxide hydrate layer of the same.